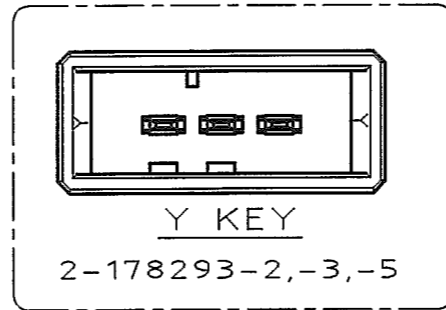
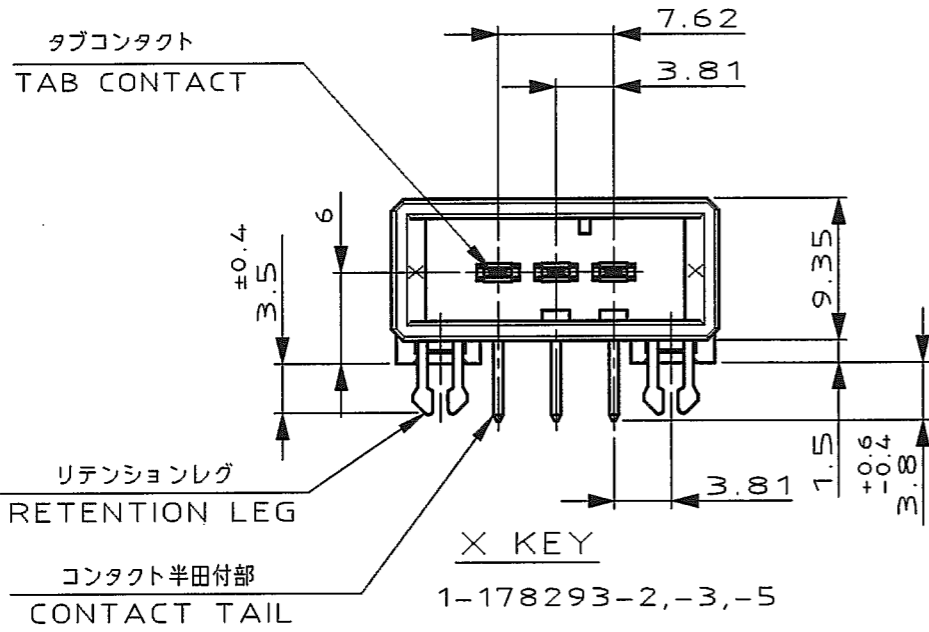
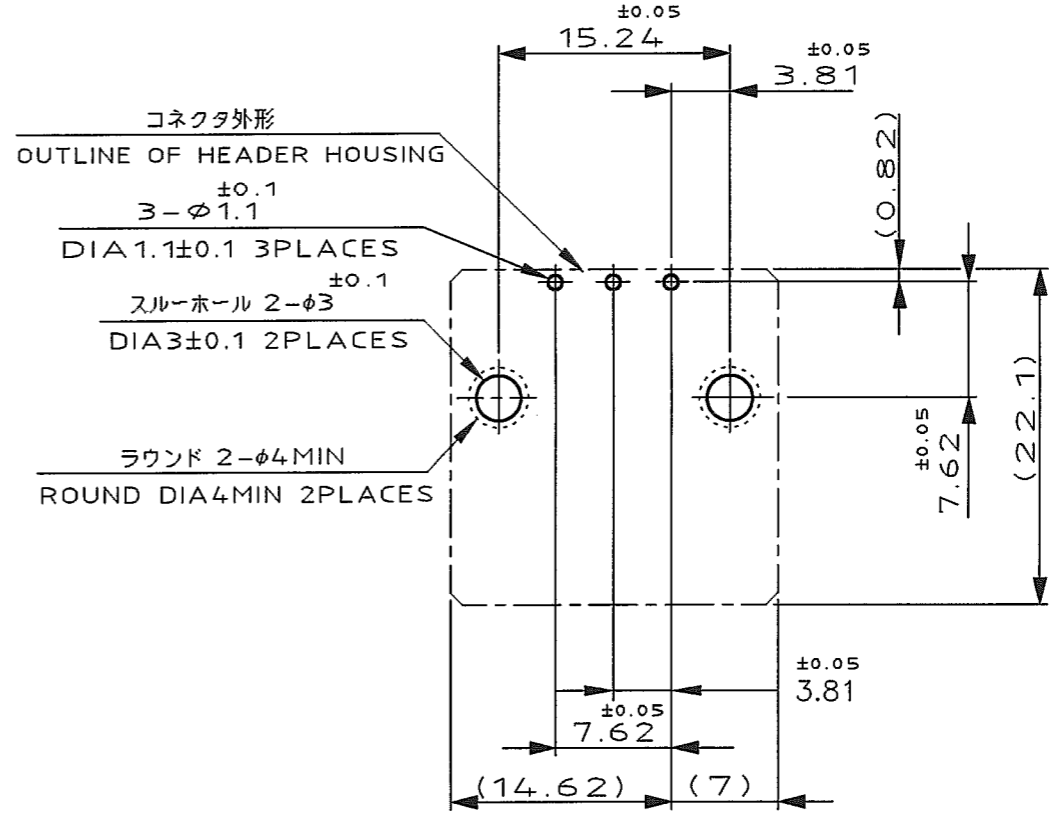
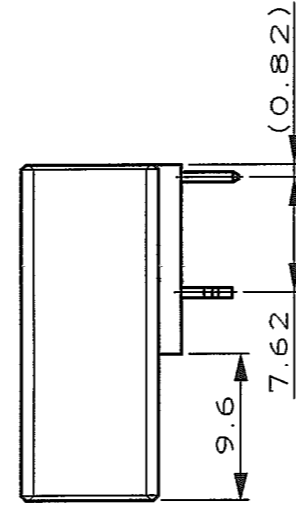
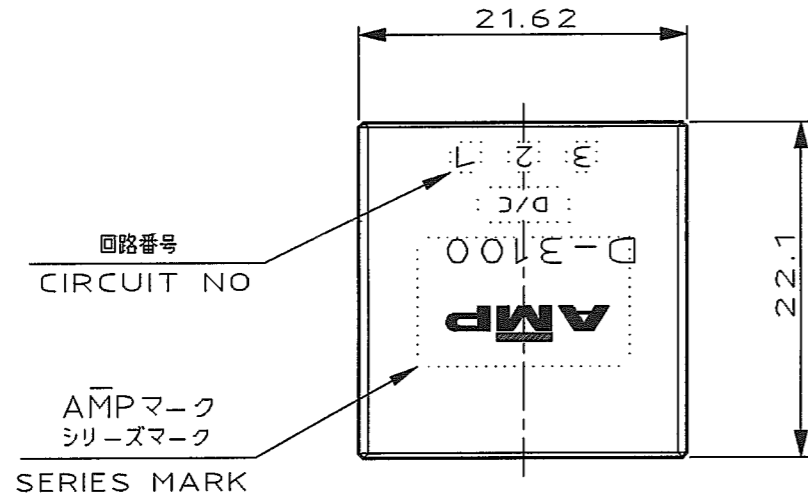


NUMBER 178293
 METRIC
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST
 AMP-J REV.10/83



推奨基板取付け穴寸法
 PC 基板厚: 1.6±0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- ~~FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
- ~~めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき~~
- めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき

△6	△4	1,2-178293-5
△6	△3	1,2-178293-3
△6	△2	1,2-178293-2
(FINISH)	製品番号 (PART NO.)	

C	REVISED (FJD0-0039-03)	TS	S.M	4/15/93
B	REVISED (FJD0-0097-03)	TS	S.M	4/15/93
A	REDRAWN (FJD0-2183-95)	KI	S.M	3-23/95
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm (AWG -)		mm		3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 20/MAR/95 K.IKEDA		DE. 20/MAR/95 K.IKEDA		SIZE LOC NUMBER A3 J C=178293	
CHK. 23/MAR/92 S.MANABE		APP. 23/MAR/92 S.MANABE		SCALE REV. SHEET 2-1 C 1 OF 1	

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